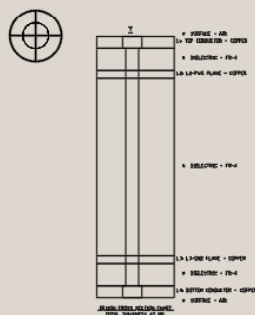
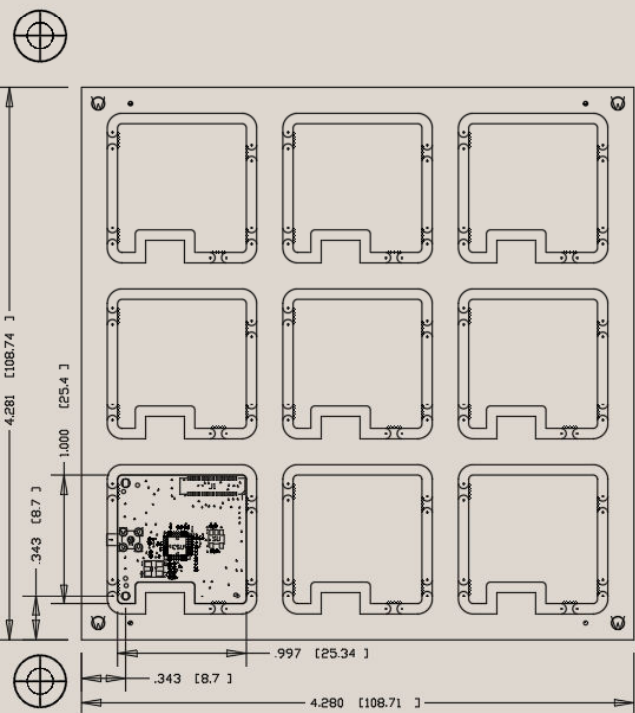


EICAD File No. Jupiter_Nano_Analog_in_R1.BRD		MANUFACTURING INFORMATION FOR PCB					
CUSTOMER: MARIS		P/N: M-P-0160-0001 REV-1.0					
LAYER STRUCTURE (from TOP to BOTTOM)							
LYR	DESCRIPTION	COPPER [Oz]	DIELECTRIC [DM]	LAYER SYM	GERBER FILE	IMPEDANCE	
1.	TOP	1.5[oz]		CS	xxx_TOP.LGX	SE=5 MIL 50 Ohm	
2.	L2-PWR	1.0		L2	xxx_L2-PWR.LGX		
3.	L3-GND	1.0		L3	xxx_L3-GND.LGX		
4.	BOTTOM	1.5[oz]		PS	xxx_BOT.LGX	SE=5 MIL 50 Ohm SE=5.5 MIL 75 Ohm Ref.to Layer L2-PWR	
[oz] - AFTER PLATING							
NOTES: UNLESS OTHERWISE SPECIFIED: 1. TOTAL THICKNESS 1.2 mm +/- 10% AFTER PLATING 2. MATERIAL: FR4 Tg=170 DEG.C MINIMUM 3. FINISHING: IMMERSION GOLD FINISH: IMMERSION GOLD 2-4 MICRO INCH THICKNESS, OVER ELECTROLESS NICKEL 150-170 MICRO INCH THICKNESS ON EXPOSED COPPER. 4. VIAS CONNECTED TO PLANE ARE DIRECT CONNECTION 5. HOLE DIAMETER IS AFTER PLATING 6. FINISHED HOLE SIZE TOLERANCE: +/-0.003" 7. VIA HOLE SIZE MAY BE MODIFIED BY MANUFACTURER 8. UNUSED VIA MAY REMOVED AS PRODUCTION NEEDS				9. PCB MFR SHOULD CLEAN SILKSCREEN BY SOLDER MASK 10. IN CASE OF CONFLICT BETWEEN MECHANICAL DIMENSIONS AND BOARD OUTLINE, GERBER FILE xxx_BRD.LGX IS GOVERN 11. THE MANUFACTURER MAY WILL ADD TEAR DROPS IN ALL SIGNAL LAYERS IF NEEDED. 12. THE MANUFACTURER WILL ADD MANUFACTURER CODE, (FSCM) DATE AND UL-CODE IN P.S.ONLY. 13. ALL DIMENSIONS ARE IN INCH (mm) 14. FINISH BOARD SHALL MEET THE PERFORMANCE REQUIREMENTS OF IPC-6012 CLASS 2. 15. REMOVE ALL BURRS AND BREAK SHARP EDGES .015 INCH MAXIMUM.		16. BOARD BOW, WARP OR TWIST SHALL NOT EXCEED +/- 0.0075 PER INCH MEASURED IN ACCORDANCE WITH IPC-TM-650, METHOD 2.4.22. 17. CONTROLLED IMPEDANCE +/- 10% <input checked="" type="checkbox"/> YES <input type="checkbox"/> NO 18. PERFORM VCUT AS PER VIEWA <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO 19. DO NESTING (BREAKAWAY) AS PER DRAWING <input checked="" type="checkbox"/> YES <input type="checkbox"/> NO 20. RoHS COMPLIANCE: 20.1 RoHS COMPLIANT MARK/STAMP ON EACH PCB FRAME 20.2 RoHS COMPLIANT ON EACH PCB SEALED BAG/PACKAGE 20.3 IN ALL PACKAGING LEVELS AND SHIPPING DOCUMENTS IT SHOULD BE MARKED WITH A VISIBLE RoHS COMPLIANT MARK OR LABEL 20.4 C.D.C.SHOULD INCLUDE A DECLARATION THAT THE PCB'S ARE RoHS COMPLIANT	
ELECTRICAL TEST				GERBER FILES NAME CONVENTION: XXXXXYY.LGX LAYER CODE BOARD NAME			
ELECTRICAL TEST FILE: xxx.IPC (IPC356D FORMAT) IF FILE xxx.IPC IS MISSING PLEASE DO NOT PRODUCE THIS BOARD AND CALL ELCAD							
Artwork by ELCAD PCB Ltd Tel: Office: 972-8-941-7274, 972-8-941-7284 CP: 972-522-560-866, e-mail: elcad@zahav.net.il							



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	9.8	+2.0/-4.0	PLATED	89
.	10.0	+2.0/-4.0	PLATED	5
o	20.0	+2.0/-2.0	PLATED	1
Δ	33.0	+2.0/-2.0	PLATED	4
.	16.0	+4.0/-0.0	NON-PLATED	225
U	65.0	+4.0/-0.0	NON-PLATED	2
W	98.0	+4.0/-4.0	NON-PLATED	4

TOTAL HOLES: 330